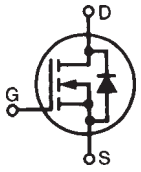
IXYS

TrenchHV™ Power MOSFET

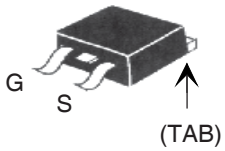
IXTA42N15T
IXTP42N15T

V_{DSS} = 150V
I_{D25} = 42A
$R_{DS(on)}$ ≤ 45mΩ

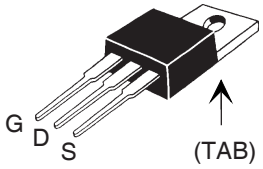
N-Channel Enhancement Mode
Avalanche Rated



TO-263



TO-220



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	150	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	150	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C	42	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	100	A
I_A	T_C = 25°C	5	A
E_{AS}	T_C = 25°C	400	mJ
P_D	T_C = 25°C	200	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6mm (0.062in.) from case for 10s	300	°C
T_{SOLD}	Plastic body for 10 seconds	260	°C
M_d	Mounting torque (TO-220)	1.13 / 10	Nm/lb.in.
Weight	TO-263	2.5	g
	TO-220	3.0	g

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250μA	150			V
$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	2.5		4.5	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V			±100	nA
I_{DSS}	V_{DS} = V_{DSS}			5	μA
	V_{GS} = 0V T_J = 150°C			150	μA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 0.5 • I_{D25}, Notes 1, 2		38	45	mΩ

Features

- International standard packages
- 175°C Operating Temperature
- Avalanche rated

Advantages

- Easy to mount
- Space savings
- High power density

Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor drives
- Uninterruptible power supplies
- High speed power switching applications

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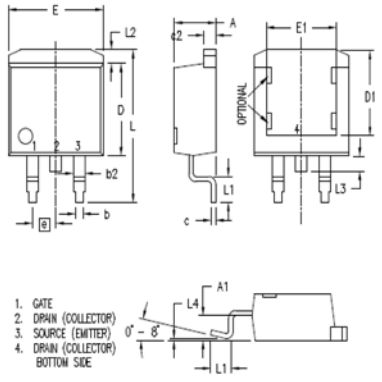
Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 0.5 • I_{D25}, Note 1	20	33		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		1880		pF
C_{oss}			255		pF
C_{rss}			37		pF
$t_{d(on)}$	**Resistive Switching Times**		14		ns
t_r	V_{GS} = 15V, V_{DS} =0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		16		ns
$t_{d(off)}$	R_G = 10Ω (External)		50		ns
t_f			25		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		21		nC
Q_{gs}			6.0		nC
Q_{gd}			6.6		nC
R_{thJC}				0.75	°C/W
R_{thCH}	TO-220		0.50		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			42	A
I_{SM}	Repetitive, Pulse width limited by T_{JM}			126	A
V_{SD}	I_F = 21A, V_{GS} = 0V, Note 1			1.1	V
t_{rr}	I_F = 25A, V_{GS} = 0V, -di/dt = 100A/μs, V_R = 50V		100		ns

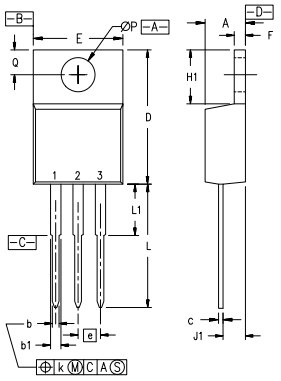
Notes: 1. Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.
2. On through-hole packages, $R_{DS(on)}$ Kelvin test contact location must be 5mm or less from the package body.

TO-263 (IXTA) Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100 BSC		2.54 BSC	
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

TO-220 (IXTP) Outline



Pins: 1 - Gate 2 - Drain
3 - Source 4 - Drain

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,850,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ 25ºC

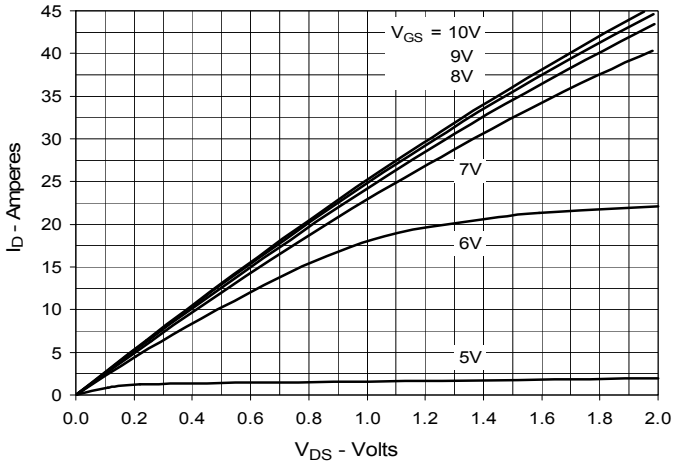


Fig. 2. Extended Output Characteristics @ 25ºC

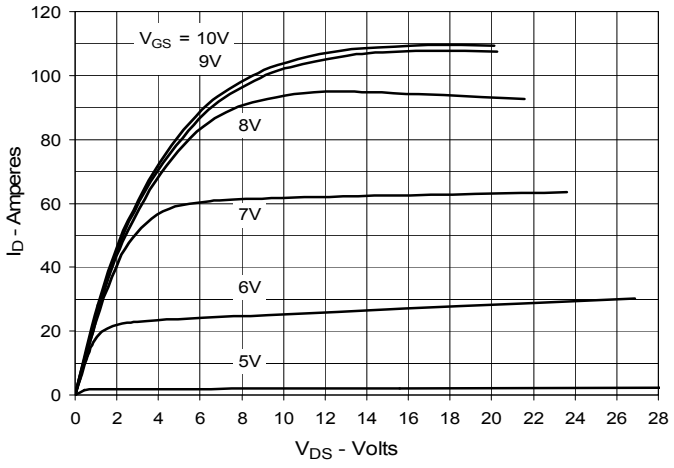


Fig. 3. Output Characteristics @ 150ºC

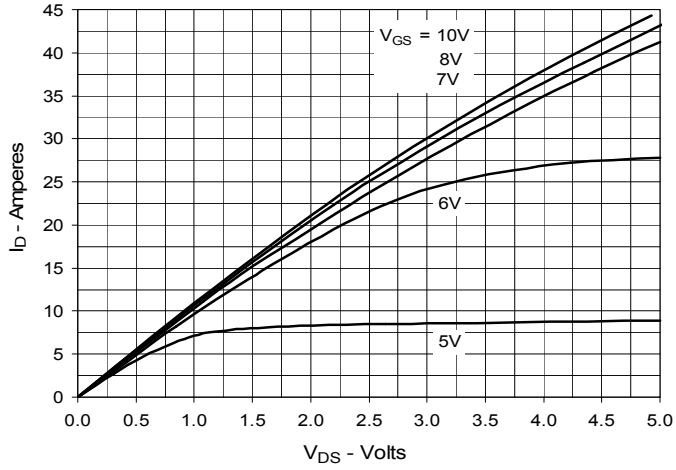


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 21A Value vs. Junction Temperature

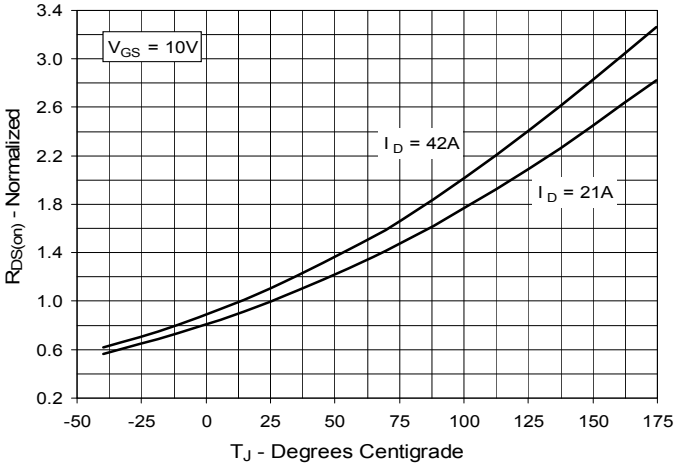


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 21A Value vs. Drain Current

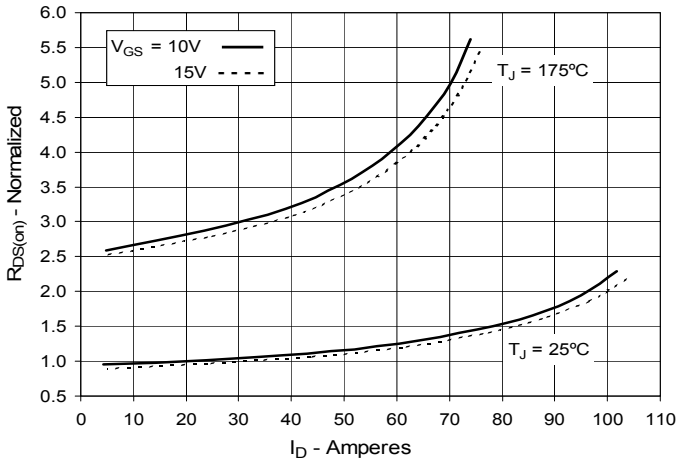
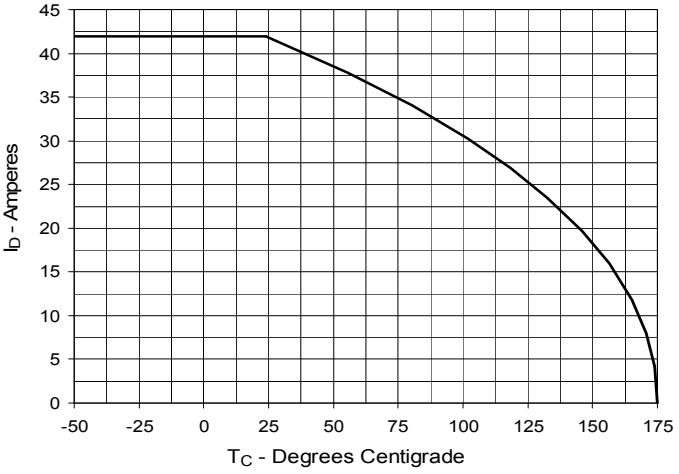


Fig. 6. Drain Current vs. Case Temperature



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Fig. 7. Input Admittance

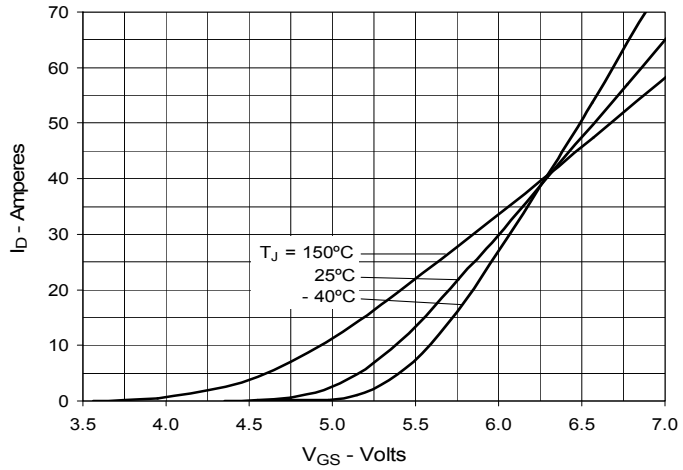


Fig. 8. Transconductance

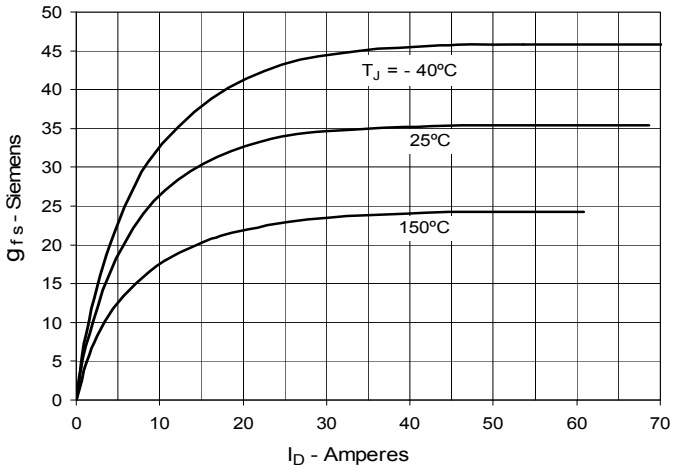


Fig. 9. Forward Voltage Drop of Intrinsic Diode

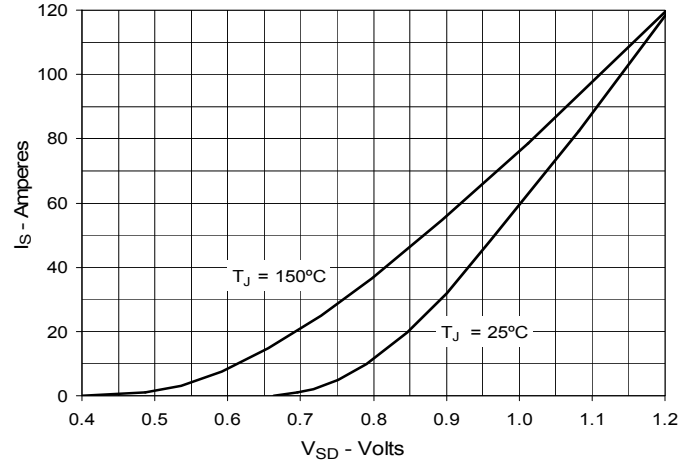


Fig. 10. Gate Charge

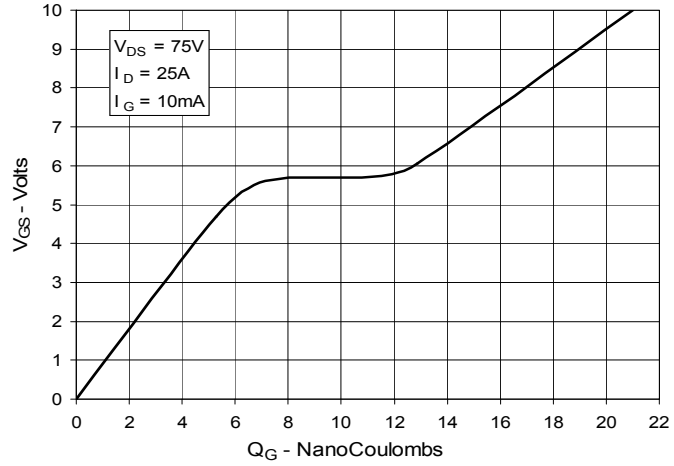


Fig. 11. Capacitance

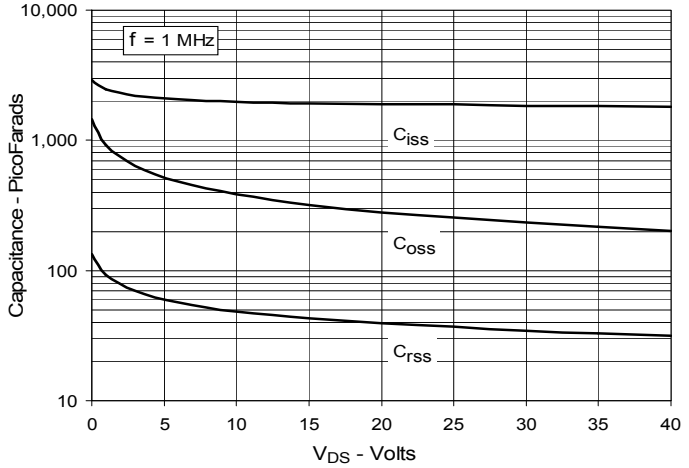
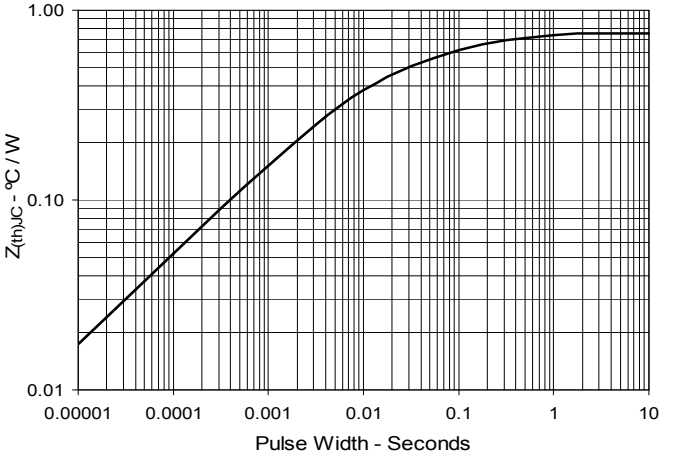


Fig. 12. Maximum Transient Thermal Impedance



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Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

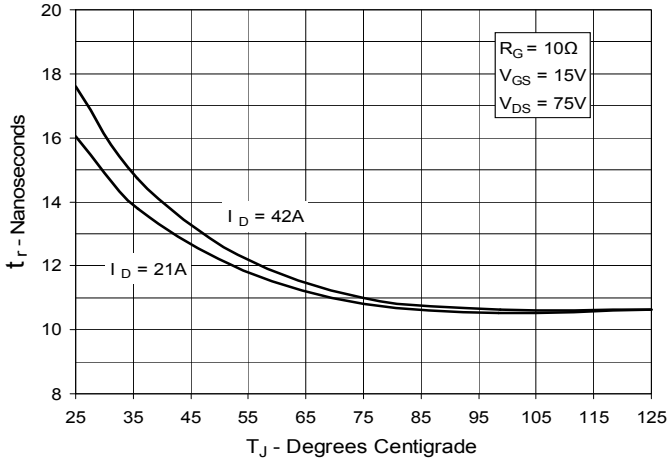


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

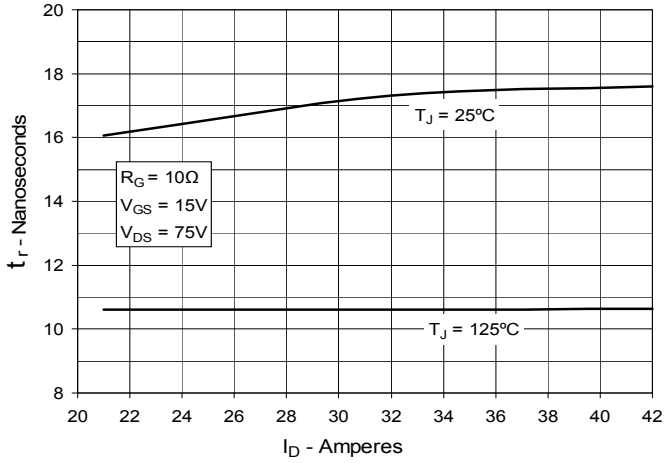


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

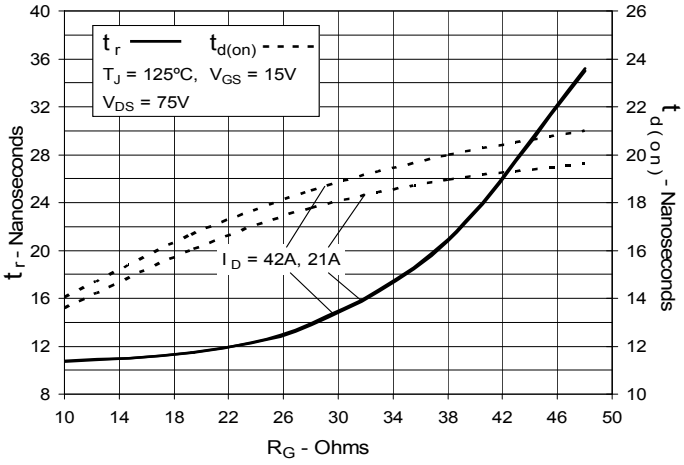


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

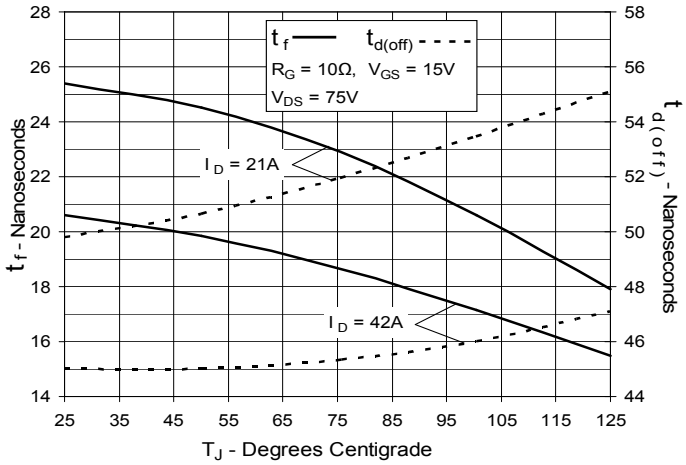


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

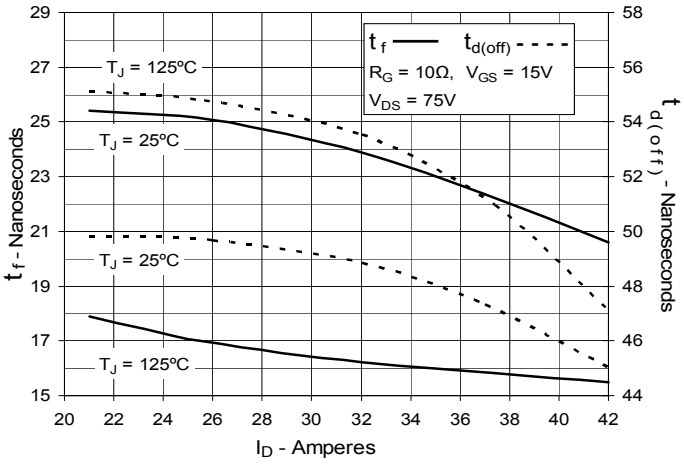
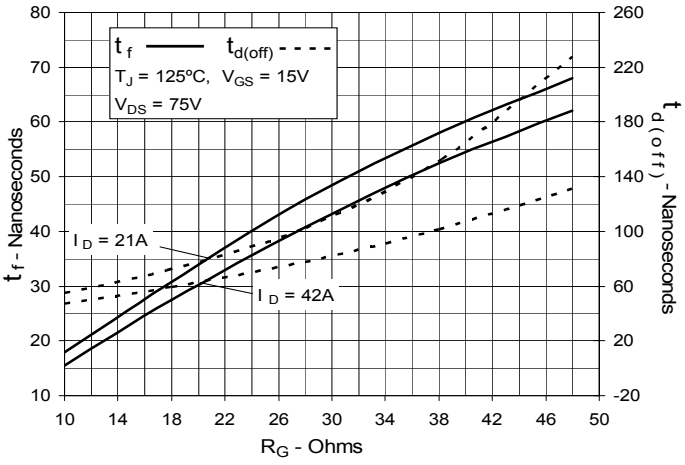


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance



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